

74HC595D

1. Functional Description

- 8-Bit Shift Register/Latch (3-state)

2. General

The 74HC595D is a high speed 8-BIT SHIFT REGISTER/LATCH fabricated with silicon gate C²MOS technology. It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

The 74HC595D contains an 8-bit static shift register which feeds an 8-bit storage register.

Shift operation is accomplished on the positive going transition of the SCK input. The output register is loaded with the contents of the shift register on the positive going transition of the RCK input. Since RCK and SCK signals are independent, parallel outputs can be held stable during the shift operation.

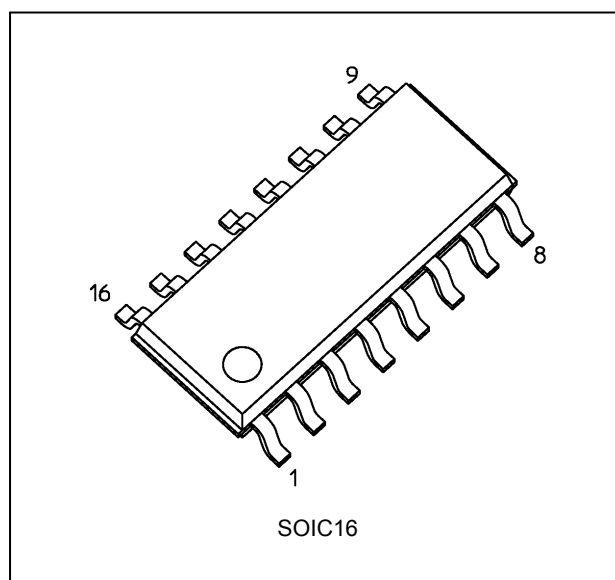
And, since the parallel outputs are 3-state, it can be directly connected to 8-bit bus. This register can be used in serial-to-parallel conversion, data receivers, etc.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

3. Features

- (1) High speed: $f_{\text{MAX}} = 55 \text{ MHz}$ (typ.) at $V_{\text{CC}} = 5 \text{ V}$
- (2) Low power dissipation: $I_{\text{CC}} = 4.0 \mu\text{A}$ (max) at $T_a = 25^\circ\text{C}$
- (3) Balanced propagation delays: $t_{\text{PLH}} \approx t_{\text{PHL}}$
- (4) Wide operating voltage range: $V_{\text{CC(opr)}} = 2.0 \text{ V}$ to 6.0 V

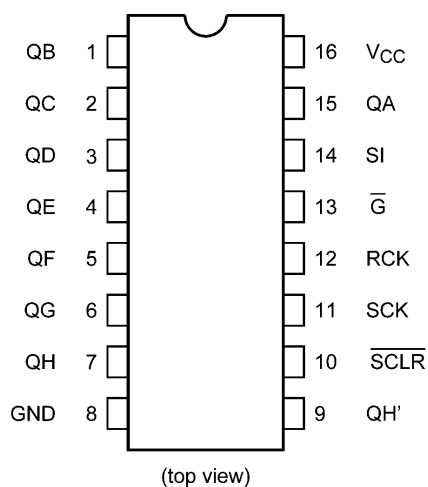
4. Packaging



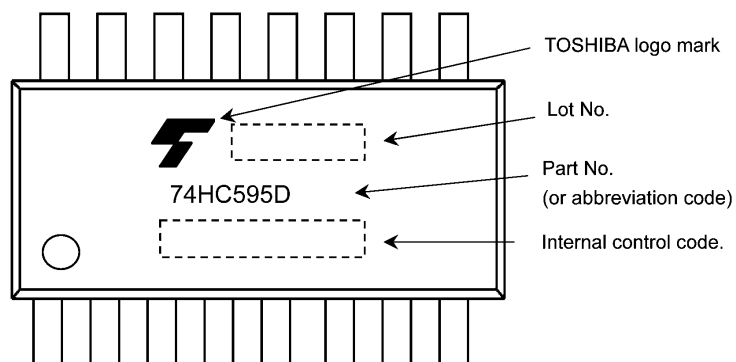
Start of commercial production

2016-02

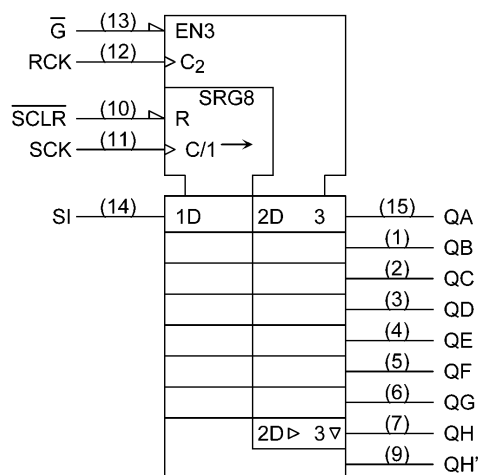
5. Pin Assignment








6. Marking



7. IEC Logic Symbol

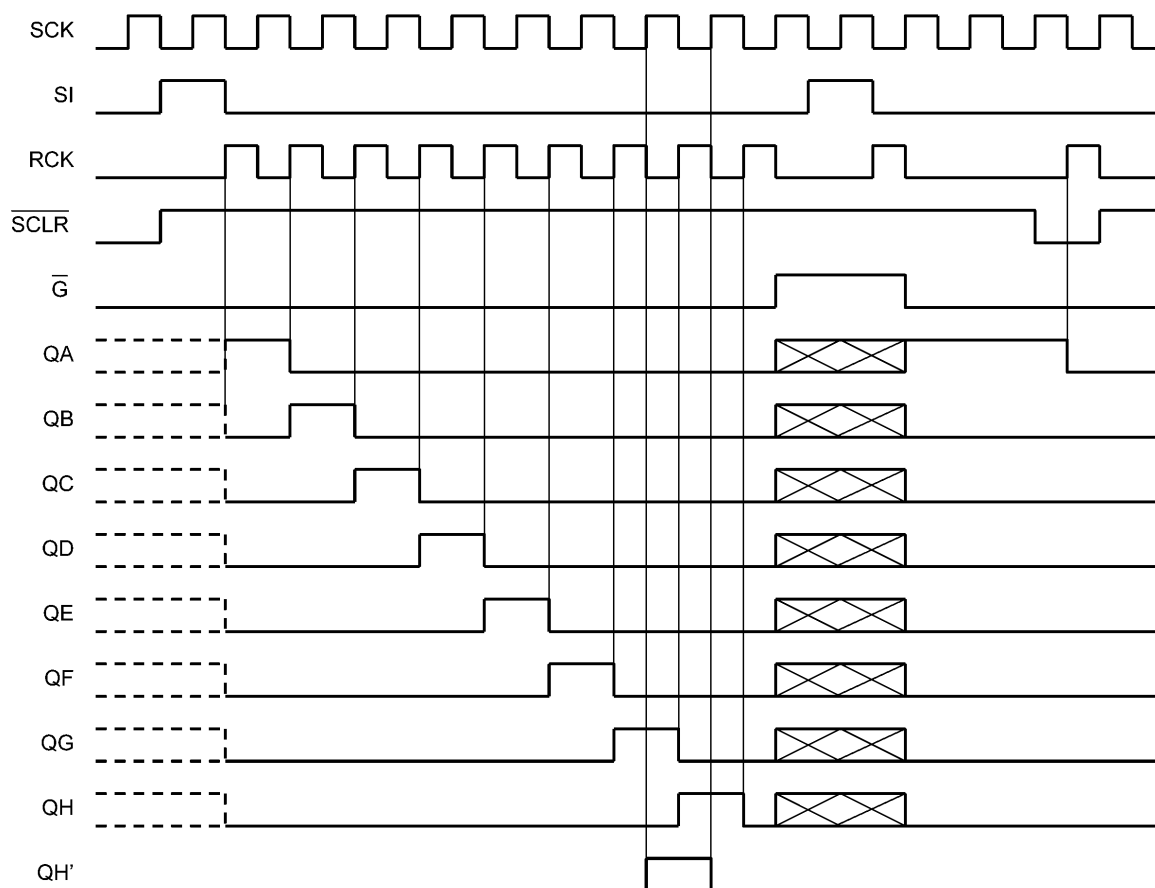


8. Truth Table

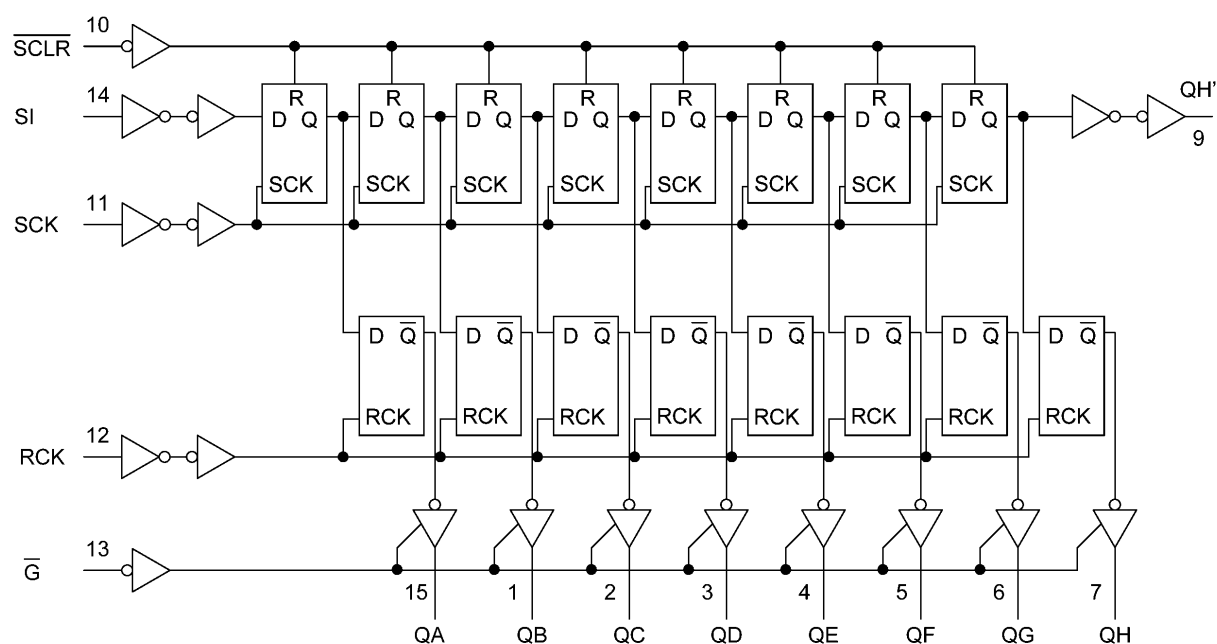
Inputs					Function
SI	SCK	$\overline{\text{SCLR}}$	RCK	$\overline{\text{G}}$	
X	X	X	X	H	QA thru QH outputs disable
X	X	X	X	L	QA thru QH outputs enable
X	X	L	X	X	Shift register is cleared.
L		H	X	X	First stage of S.R. becomes "L". Other stages store the data of previous stage, respectively.
H		H	X	X	First stage of S.R. becomes "H". Other stages store the data of previous stage, respectively.
X		H	X	X	State of S.R. is not changed.
X	X	X		X	S.R. data is stored into storage register.
X	X	X		X	Storage register stage is not changed.

X: Don't care

9. Timing Chart



10. System Diagram



11. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V_{CC}		-0.5 to 7.0	V
Input voltage	V_{IN}		-0.5 to $V_{CC} + 0.5$	V
Output voltage	V_{OUT}		-0.5 to $V_{CC} + 0.5$	V
Input diode current	I_{IK}		± 20	mA
Output diode current	I_{OK}		± 20	mA
Output current (QH')	I_{OUT}		± 25	mA
Output current (QA to QH)			± 35	mA
V_{CC} /ground current	I_{CC}		± 75	mA
Power dissipation	P_D	(Note 1)	500	mW
Storage temperature	T_{stg}		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: P_D derates linearly with -8 mW/°C above 85 °C

12. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V_{CC}	—	2.0 to 6.0	V
Input voltage	V_{IN}	—	0 to V_{CC}	V
Output voltage	V_{OUT}	—	0 to V_{CC}	V
Operating temperature	T_{opr}	—	-40 to 125	°C
Input rise and fall times	t_r, t_f	—	0 to 50	μs

Note: The operating ranges must be maintained to ensure the normal operation of the device.
Unused inputs must be tied to either V_{CC} or GND.

13. Electrical Characteristics

13.1. DC Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	—	V
				4.5	3.15	—	—	
				6.0	4.20	—	—	
Low-level input voltage	V_{IL}	—		2.0	—	—	0.50	V
				4.5	—	—	1.35	
				6.0	—	—	1.80	
High-level output voltage	V_{OH}	$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20\text{ }\mu\text{A}$	2.0	1.9	2.0	—	V
				4.5	4.4	4.5	—	
				6.0	5.9	6.0	—	
High-level output voltage QH'			$I_{OH} = -4\text{ mA}$	4.5	4.18	4.31	—	
			$I_{OH} = -5.2\text{ mA}$	6.0	5.68	5.80	—	
High-level output voltage QA to QH			$I_{OH} = -6\text{ mA}$	4.5	4.18	4.31	—	
			$I_{OH} = -7.8\text{ mA}$	6.0	5.68	5.80	—	
Low-level output voltage	V_{OL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20\text{ }\mu\text{A}$	2.0	—	0.0	0.1	V
				4.5	—	0.0	0.1	
				6.0	—	0.0	0.1	
Low-level output voltage QH'			$I_{OL} = 4\text{ mA}$	4.5	—	0.17	0.26	
			$I_{OL} = 5.2\text{ mA}$	6.0	—	0.18	0.26	
Low-level output voltage QA to QH			$I_{OL} = 6\text{ mA}$	4.5	—	0.17	0.26	
			$I_{OL} = 7.8\text{ mA}$	6.0	—	0.18	0.26	
3-state output OFF-state leakage current	I_{OZ}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{OUT} = V_{CC} \text{ or } \text{GND}$		6.0	—	—	± 0.5	μA
Input leakage current	I_{IN}	$V_{IN} = V_{CC} \text{ or } \text{GND}$		6.0	—	—	± 0.1	μA
Quiescent supply current	I_{CC}	$V_{IN} = V_{CC} \text{ or } \text{GND}$		6.0	—	—	4.0	μA

13.2. DC Characteristics (Unless otherwise specified, $T_a = -40$ to $85\text{ }^\circ\text{C}$)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	V
				4.5	3.15	—	
				6.0	4.20	—	
Low-level input voltage	V_{IL}	—		2.0	—	0.50	V
				4.5	—	1.35	
				6.0	—	1.80	
High-level output voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -20\text{ }\mu\text{A}$	2.0	1.9	—	V
				4.5	4.4	—	
				6.0	5.9	—	
High-level output voltage QH'			$I_{OH} = -4\text{ mA}$	4.5	4.13	—	
			$I_{OH} = -5.2\text{ mA}$	6.0	5.63	—	
High-level output voltage QA to QH			$I_{OH} = -6\text{ mA}$	4.5	4.13	—	
			$I_{OH} = -7.8\text{ mA}$	6.0	5.63	—	
Low-level output voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 20\text{ }\mu\text{A}$	2.0	—	0.1	V
				4.5	—	0.1	
				6.0	—	0.1	
Low-level output voltage QH'			$I_{OL} = 4\text{ mA}$	4.5	—	0.33	
			$I_{OL} = 5.2\text{ mA}$	6.0	—	0.33	
Low-level output voltage QA to QH			$I_{OL} = 6\text{ mA}$	4.5	—	0.33	
			$I_{OL} = 7.8\text{ mA}$	6.0	—	0.33	
3-state output OFF-state leakage current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND		6.0	—	± 5.0	μA
Input leakage current	I_{IN}	$V_{IN} = V_{CC}$ or GND		6.0	—	± 1.0	μA
Quiescent supply current	I_{CC}	$V_{IN} = V_{CC}$ or GND		6.0	—	40.0	μA

13.3. DC Characteristics (Unless otherwise specified, $T_a = -40$ to $125\text{ }^{\circ}\text{C}$)

Characteristics	Symbol	Test Condition		V_{CC} (V)	Min	Max	Unit
High-level input voltage	V_{IH}	—		2.0	1.50	—	V
				4.5	3.15	—	
				6.0	4.20	—	
Low-level input voltage	V_{IL}	—		2.0	—	0.50	V
				4.5	—	1.35	
				6.0	—	1.80	
High-level output voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -20\text{ }\mu\text{A}$	2.0	1.9	—	V
				4.5	4.4	—	
				6.0	5.9	—	
High-level output voltage QH'			$I_{OH} = -4\text{ mA}$	4.5	3.7	—	
			$I_{OH} = -5.2\text{ mA}$	6.0	5.2	—	
High-level output voltage QA to QH			$I_{OH} = -6\text{ mA}$	4.5	3.7	—	
			$I_{OH} = -7.8\text{ mA}$	6.0	5.2	—	
Low-level output voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 20\text{ }\mu\text{A}$	2.0	—	0.1	V
				4.5	—	0.1	
				6.0	—	0.1	
Low-level output voltage QH'			$I_{OL} = 4\text{ mA}$	4.5	—	0.4	
			$I_{OL} = 5.2\text{ mA}$	6.0	—	0.4	
Low-level output voltage QA to QH			$I_{OL} = 6\text{ mA}$	4.5	—	0.4	
			$I_{OL} = 7.8\text{ mA}$	6.0	—	0.4	
3-state output OFF-state leakage current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND		6.0	—	± 10.0	μA
Input leakage current	I_{IN}	$V_{IN} = V_{CC}$ or GND		6.0	—	± 1.0	μA
Quiescent supply current	I_{CC}	$V_{IN} = V_{CC}$ or GND		6.0	—	160.0	μA

13.4. Timing Requirements (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}, t_{w(H)}$	See 14. AC Waveform, Fig. 14.2	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum pulse width ($\overline{\text{SCLR}}$)	$t_{w(L)}$	See 14. AC Waveform, Fig. 14.2	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum setup time (SI-SCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	50	ns
			4.5	10	
			6.0	9	
Minimum setup time (SCK - RCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum setup time ($\overline{\text{SCLR}}$ - RCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	100	ns
			4.5	20	
			6.0	17	
Minimum hold time	t_h	See 14. AC Waveform, Fig. 14.2	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time ($\overline{\text{SCLR}}$)	t_{rem}	See 14. AC Waveform, Fig. 14.2	2.0	50	ns
			4.5	10	
			6.0	9	
Clock frequency	f	—	2.0	6	MHz
			4.5	30	
			6.0	35	

13.5. Timing Requirements

(Unless otherwise specified, $T_a = -40$ to $85\text{ }^\circ\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}, t_{w(H)}$	See 14. AC Waveform, Fig. 14.2	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum pulse width ($\overline{\text{SCLR}}$)	$t_{w(L)}$	See 14. AC Waveform, Fig. 14.2	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum setup time (SI-SCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	65	ns
			4.5	13	
			6.0	11	
Minimum setup time (SCK - RCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum setup time ($\overline{\text{SCLR}}$ - RCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	125	ns
			4.5	25	
			6.0	21	
Minimum hold time	t_h	See 14. AC Waveform, Fig. 14.2	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time ($\overline{\text{SCLR}}$)	t_{rem}	See 14. AC Waveform, Fig. 14.2	2.0	65	ns
			4.5	13	
			6.0	11	
Clock frequency	f	—	2.0	5	MHz
			4.5	25	
			6.0	28	

13.6. Timing Requirements

(Unless otherwise specified, $T_a = -40$ to $125\text{ }^{\circ}\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Limit	Unit
Minimum pulse width (SCK, RCK)	$t_{w(L)}, t_{w(H)}$	See 14. AC Waveform, Fig. 14.2	2.0	110	ns
			4.5	22	
			6.0	19	
Minimum pulse width ($\overline{\text{SCLR}}$)	$t_{w(L)}$	See 14. AC Waveform, Fig. 14.2	2.0	110	ns
			4.5	22	
			6.0	19	
Minimum setup time (SI-SCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum setup time (SCK - RCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	110	ns
			4.5	22	
			6.0	19	
Minimum setup time ($\overline{\text{SCLR}}$ - RCK)	t_s	See 14. AC Waveform, Fig. 14.2	2.0	150	ns
			4.5	30	
			6.0	26	
Minimum hold time	t_h	See 14. AC Waveform, Fig. 14.2	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time ($\overline{\text{SCLR}}$)	t_{rem}	See 14. AC Waveform, Fig. 14.2	2.0	75	ns
			4.5	15	
			6.0	13	
Clock frequency	f	—	2.0	4	MHz
			4.5	20	
			6.0	24	

13.7. AC Characteristics

(Unless otherwise specified, $C_L = 15\text{ pF}$, $V_{CC} = 5\text{ V}$, $T_a = 25\text{ }^{\circ}\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Output transition time (QH')	t_{TLH}, t_{THL}	See 14. AC Waveform, Fig. 14.1	—	4	8	ns
Propagation delay time (SCK-QH')	t_{PLH}, t_{PHL}	See 14. AC Waveform, Fig. 14.1	—	12	21	
Propagation delay time ($\overline{\text{SCLR}}$ -QH')	t_{PHL}	See 14. AC Waveform, Fig. 14.1	—	15	30	
Maximum clock frequency	f_{MAX}	—	35	55	—	MHz

13.8. AC Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Note	Test Condition	C_L (pF)	V_{CC} (V)	Min	Typ.	Max	Unit
Output transition time (Qn)	t_{TLH}, t_{THL}		See 14. AC Waveform, Fig. 14.1	50	2.0	—	25	60	ns
					4.5	—	7	12	
					6.0	—	6	10	
Output transition time (QH')	t_{TLH}, t_{THL}		See 14. AC Waveform, Fig. 14.1	50	2.0	—	30	75	ns
					4.5	—	8	15	
					6.0	—	7	13	
Propagation delay time (SCK-QH')	t_{PLH}, t_{PHL}		See 14. AC Waveform, Fig. 14.1	50	2.0	—	45	125	ns
					4.5	—	15	25	
					6.0	—	13	21	
Propagation delay time (SCLR-QH')	t_{PHL}		See 14. AC Waveform, Fig. 14.1	50	2.0	—	60	175	ns
					4.5	—	18	35	
					6.0	—	15	30	
Propagation delay time (RCK-Qn)	t_{PLH}, t_{PHL}		See 14. AC Waveform, Fig. 14.1	50	2.0	—	60	150	ns
					4.5	—	20	30	
					6.0	—	17	26	
				150	2.0	—	75	190	
					4.5	—	25	38	
					6.0	—	22	32	
Output enable time	t_{PZL}, t_{PZH}		$R_L = 1\text{ k}\Omega$	50	2.0	—	45	135	ns
					4.5	—	15	27	
					6.0	—	13	23	
				150	2.0	—	60	175	
					4.5	—	20	35	
					6.0	—	17	30	
Output disable time	t_{PLZ}, t_{PHZ}		$R_L = 1\text{ k}\Omega$	50	2.0	—	30	150	ns
					4.5	—	15	30	
					6.0	—	14	26	
Maximum clock frequency	f_{MAX}		—	50	2.0	6	17	—	MHz
					4.5	30	50	—	
					6.0	35	59	—	
Input capacitance	C_{IN}		—			—	3	—	pF
Power dissipation capacitance	C_{PD}	(Note 1)	—			—	41	—	pF

Note 1: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.

$$I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}$$

13.9. AC Characteristics

(Unless otherwise specified, $T_a = -40$ to $85\text{ }^\circ\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Test Condition	C_L (pF)	V_{CC} (V)	Min	Max	Unit
Output transition time (Qn)	t_{TLH}, t_{THL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	75	ns
				4.5	—	15	
				6.0	—	13	
Output transition time (QH')	t_{TLH}, t_{THL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	95	ns
				4.5	—	19	
				6.0	—	16	
Propagation delay time (SCK-QH')	t_{PLH}, t_{PHL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	155	ns
				4.5	—	31	
				6.0	—	26	
Propagation delay time (SCLR-QH')	t_{PHL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	220	ns
				4.5	—	44	
				6.0	—	37	
Propagation delay time (RCK-Qn)	t_{PLH}, t_{PHL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	190	ns
				4.5	—	38	
				6.0	—	32	
			150	2.0	—	240	
				4.5	—	48	
				6.0	—	41	
Output enable time	t_{PZL}, t_{PZH}	$R_L = 1\text{ k}\Omega$	50	2.0	—	170	ns
				4.5	—	34	
				6.0	—	29	
			150	2.0	—	220	
				4.5	—	44	
				6.0	—	37	
Output disable time	t_{PLZ}, t_{PHZ}	$R_L = 1\text{ k}\Omega$	50	2.0	—	190	ns
				4.5	—	38	
				6.0	—	33	
Maximum clock frequency	f_{MAX}	—	50	2.0	5	—	MHz
				4.5	25	—	
				6.0	28	—	

13.10. AC Characteristics

(Unless otherwise specified, $T_a = -40$ to $125\text{ }^{\circ}\text{C}$, Input: $t_r = t_f = 6\text{ ns}$)

Characteristics	Symbol	Test Condition	C_L (pF)	V_{CC} (V)	Min	Max	Unit
Output transition time (Qn)	t_{TLH}, t_{THL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	90	ns
				4.5	—	18	
				6.0	—	15	
Output transition time (QH')	t_{TLH}, t_{THL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	115	ns
				4.5	—	23	
				6.0	—	20	
Propagation delay time (SCK-QH')	t_{PLH}, t_{PHL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	240	ns
				4.5	—	48	
				6.0	—	31	
Propagation delay time (SCLR-QH')	t_{PHL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	265	ns
				4.5	—	53	
				6.0	—	45	
Propagation delay time (RCK-Qn)	t_{PLH}, t_{PHL}	See 14. AC Waveform, Fig. 14.1	50	2.0	—	265	ns
				4.5	—	53	
				6.0	—	45	
			150	2.0	—	285	
				4.5	—	57	
				6.0	—	48	
Output enable time	t_{PZL}, t_{PZH}	$R_L = 1\text{ k}\Omega$	50	2.0	—	225	ns
				4.5	—	45	
				6.0	—	38	
			150	2.0	—	265	
				4.5	—	53	
				6.0	—	45	
Output disable time	t_{PLZ}, t_{PHZ}	$R_L = 1\text{ k}\Omega$	50	2.0	—	225	ns
				4.5	—	45	
				6.0	—	38	
Maximum clock frequency	f_{MAX}	—	50	2.0	4	—	MHz
				4.5	20	—	
				6.0	24	—	

14. AC Waveform

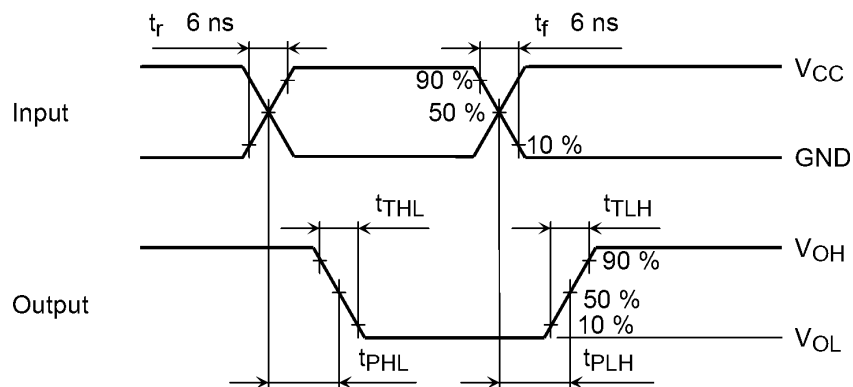


Fig. 14.1 t_{TLH} , t_{THL} , t_{PLH} , t_{PHL}

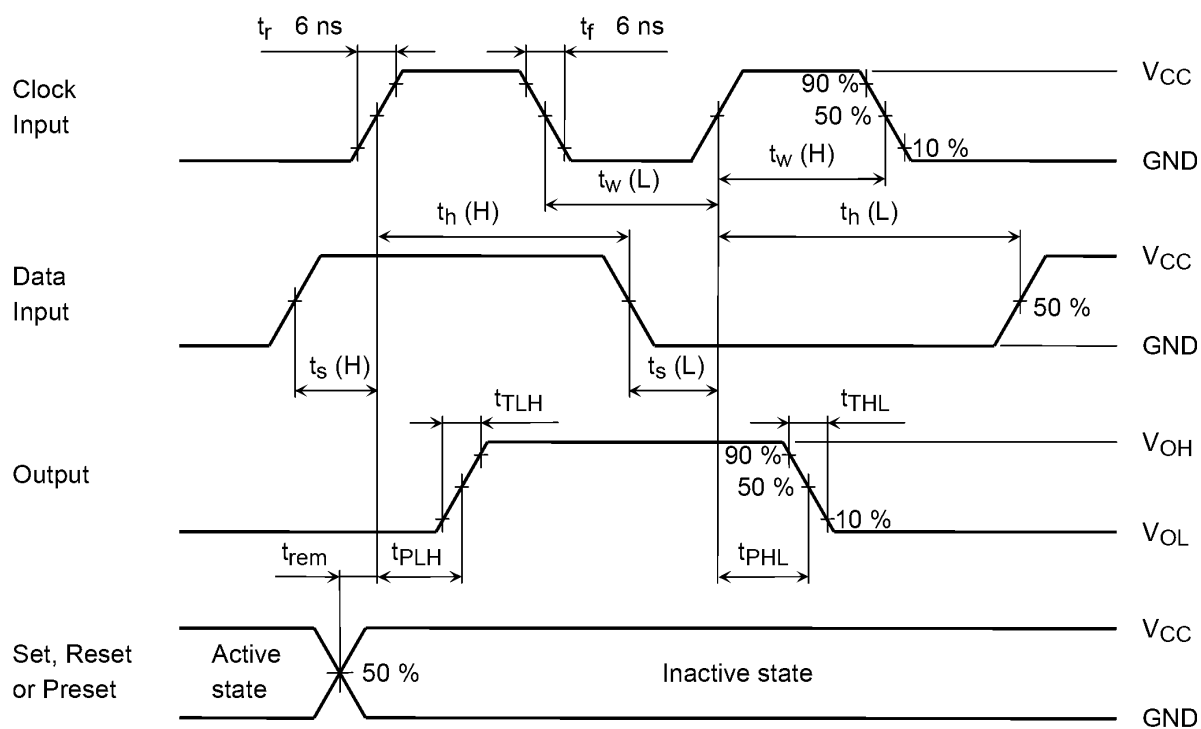
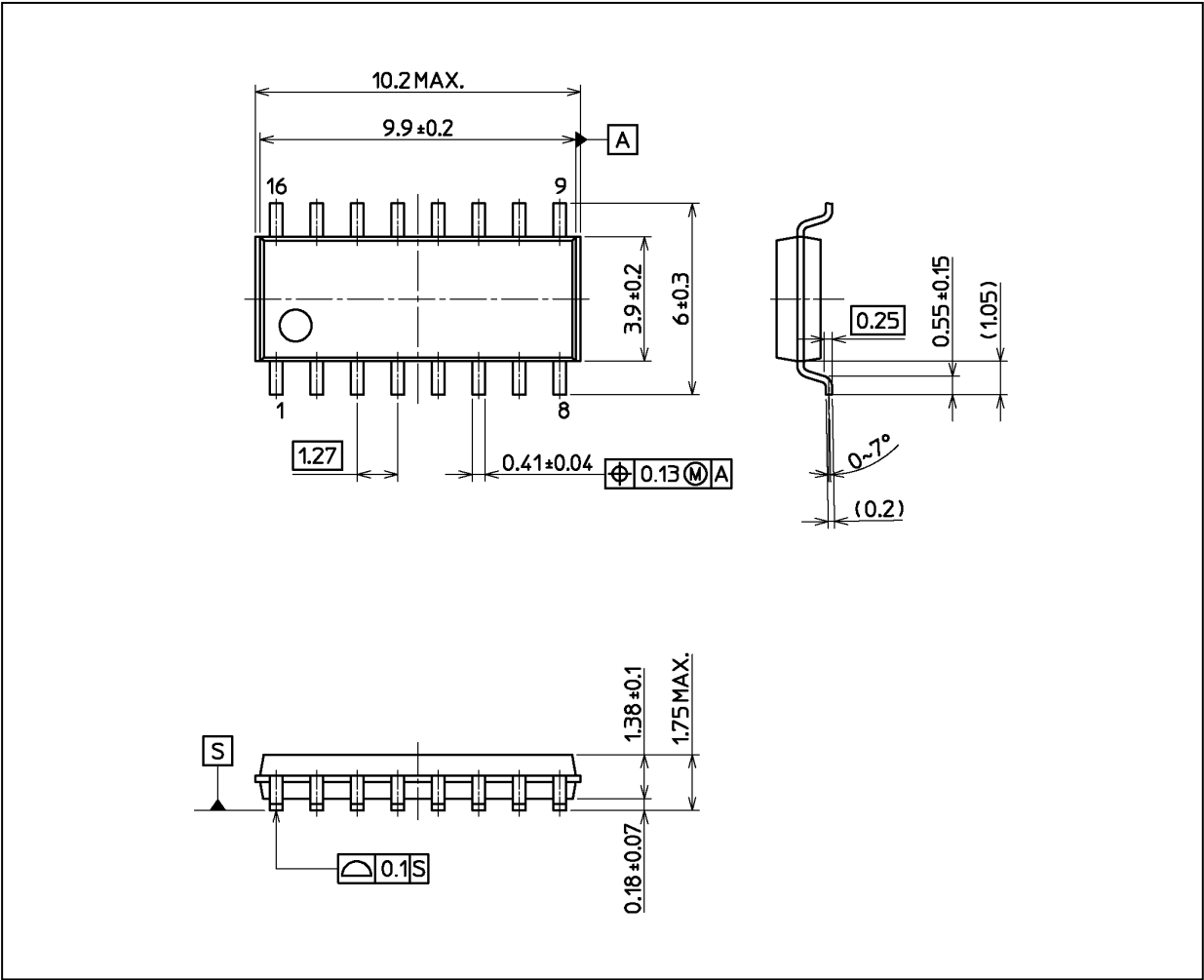


Fig. 14.2 t_w , t_s , t_h , t_{rem}

Package Dimensions

Unit: mm



Weight: 0.15 g (typ.)

Package Name(s)
Nickname: SOIC16

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